

# SKKR 800/0.1 - BVR



**SEMITRANS® 5**

## Shunt Modules

### SKKR 800/0.1 - BVR

#### Features

- Low inductance value
- Excellent long term stability
- Isolated copper baseplate using DCB (Direct Copper Bonding) Technology
- Large clearance (13 mm) and creepage distance (20 mm)
- Using BVR Shunts for extended lifetime

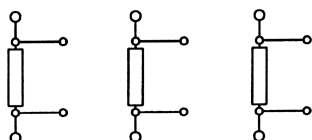
#### Typical Applications

- Current sensor for frequency converter

Absolute Maximum Ratings		T <sub>c</sub> = 25 °C, unless otherwise specified	
Symbol	Conditions	Values	Units
I <sub>DCmax</sub>	T <sub>shunt</sub> = 150 °C; T <sub>C</sub> = 25(80) °C	270 (400)	A
I <sub>SC</sub>	t <sub>sc</sub> = 10 μs	600	A
R <sub>shunt</sub>	Toleranz = ± 5%	0,263	mΩ
T <sub>cr(shunt)</sub>	temperature coefficient (20-60) °C	50	ppm/K
P <sub>tot</sub>	per shunt; T <sub>C</sub> = 25(80) °C	18 (60)	W
T <sub>stg</sub>		- 40 ... + 125	°C
V <sub>isol</sub>	AC, 1 min., I <sub>ISO</sub> = 1 mA	2500	V
humidity	IEC-EN 60 721-3-3		
climate	IEC 68 T.1	40/126/56	

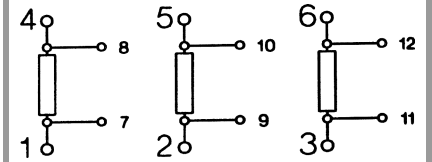
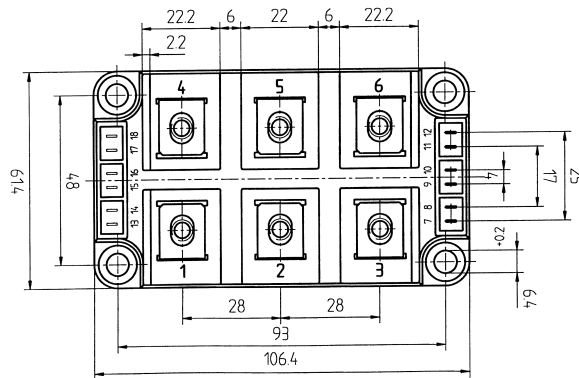
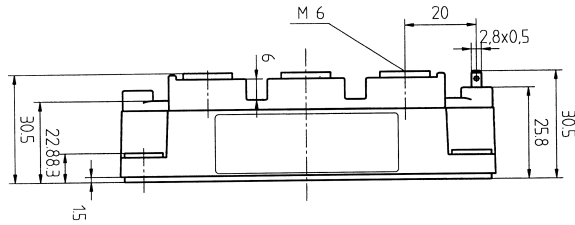
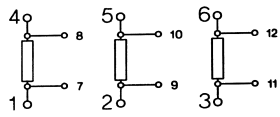
Characteristics		T <sub>c</sub> = 25 °C, unless otherwise specified			
Symbol	Conditions	min.	typ.	max.	Units
V <sub>7-8</sub>	I <sub>DC</sub> = 600 A; T <sub>C</sub> = 25(125) °C	143	150	157,5	mV
V <sub>9-10</sub>	I <sub>DC</sub> = 600 A; T <sub>C</sub> = 25(125) °C	143	150	157,5	mV
V <sub>11-12</sub>	I <sub>DC</sub> = 600 A; T <sub>C</sub> = 25(125) °C	143	150	157,5	mV
C <sub>shunt/C</sub>			280		pF
L <sub>tray</sub>	I <sub>C</sub> = 100 A; V <sub>CE</sub> = 600 V (turn off single IGBT)			0,4	nF
Thermal characteristics					
R <sub>th(j-c)</sub>				7,0	K/W

Mechanical Data		min.	typ.	max.	Units
M <sub>1</sub>	to heatsink, SI Units (M6)	3		5	Nm
	to heatsink, US Units	27		44	lb.in.
M <sub>2</sub>	to heatsink, SI Units (M6)	2,5		5	Nm
	to heatsink, US Units	22		44	lb.in.
a				5x9,81	m/s <sup>2</sup>
w				420	g



# SKKR 800/0.1 - BVR

Dimensions in mm



SKKR

Case D 97

Case D 97

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

This technical information specifies semiconductor devices but promises no characteristics. No warranty or guarantee expressed or implied is made regarding delivery, performance or suitability.